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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

INVENTORS: Kazutaka HABU; Naoko TAKEDA

ATTORNEY DOCKET NO.: 09792909-5360

SERIAL NO.: ~~Not yet assigned~~ 10/071 320

GROUP ART UNIT: ~~Not yet assigned~~ 1742

FILED: February 8, 2002

EXAMINER: ~~Not yet assigned~~ IP

TITLE: "METHOD TO MANUFACTURE LEAD-FREE SOLDER MATERIAL
HAVING GOOD WETTABILITY" (as amended)

PRELIMINARY AMENDMENT "A" TO DIVISIONAL

BOX Patent Application
Assistant Commissioner for Patents
Washington, D.C. 20231

S I R:

This is a preliminary amendment to the 37 CFR 1.53(b) Divisional filed on
February 8, 2002.

IN THE TITLE

Please amend the title of the invention to read --METHOD TO MANUFACTURE
5 LEAD-FREE SOLDER MATERIAL HAVING GOOD WETTABILITY--.

IN THE SPECIFICATION

On page 1, between lines 2 and 3, please insert the following paragraph:

---RELATED APPLICATION DATA

A1
This application claims priority to Japanese Application No. P09-348212, filed
10 December 17, 1997, and is a divisional of United States Application Serial No. 09/066,851,
filed April 28, 1998, each of which is incorporated herein by reference to the extent permitted
by law.--

IN THE CLAIMS

Please cancel claims 1-4 in favor of new claims 5-44. Please add new claims 5-44 as
15 follows:

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